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Docket No. 59970 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Y. Lin et al.

U.S. SERIAL NO.: 10/674,317

GROUP: 2841

FILED: September 29, 2003

EXAMINER: I. Carpio

FOR: GROUND PAD STRUCTURE FOR PREVENTING SOLDER
EXTRUSION AND SEMICONDUCTOR PACKAGE HAVING THE
GROUND PAD STRUCTURE

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on August 28, 2006.

By: 

Steven M. Jensen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated April 26, 2006 of the above-referenced application. A request for a one-month extension of time is submitted herewith. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.